

# MECHANICAL CASE OUTLINE

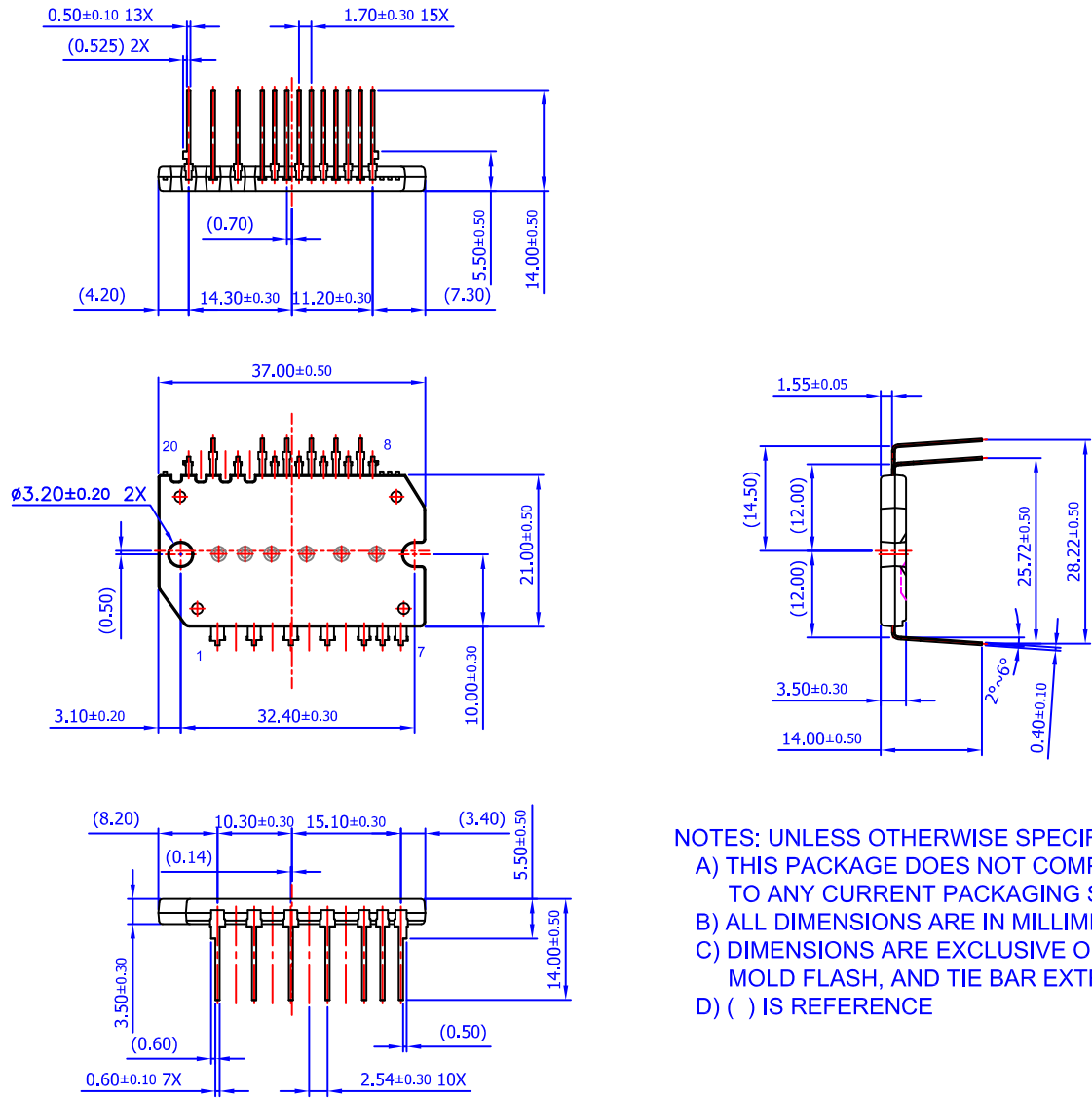
## PACKAGE DIMENSIONS

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### SPMFA-B20 / 20LD, PDD STD, FULL PACK, DOUBLE DIP CASE MODER ISSUE 0

DATE 31 JAN 2017



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